• Contamination Overview
• Effects of Contamination on Flight Hardware
• Contamination Requirements
• Design Methodology
• Integration and Testing
• Launch Site Support
• Contamination Control & Prevention
Contamination Overview
There are 2 types of Contamination

- **Particulate**: dust, debris, skin cells, fibers
- **Molecular**: films, greases, skin oils, ice
In order to mitigate performance degradation of space flight hardware caused by contamination, a Contamination Control Program is established on the Mission.

- Understand the design: what are the critical components, what are their sensitivities, and their performance requirements
- How can the S/C & instrument design help mitigate contamination
- Establish a Contamination Control Program
- Implement contamination control protocols
- Clean, monitor, verify, and maintain cleanliness
Why do we Have Contamination Requirements?

• Meet Mission and Science Objectives
• Maintain Long-Term Hardware Performance
• Prevent Against Cross-Contamination Across the S/C
• Maintain Cleanliness Levels
• Why are Contamination Requirements Important?
• Meet Mission Success

MISSION SUCCESS!!!
# Summary of Spacecraft Contamination Problems

<table>
<thead>
<tr>
<th>Spacecraft</th>
<th>Contamination Problem</th>
</tr>
</thead>
<tbody>
<tr>
<td>GOES (1989)</td>
<td>Excessive build-up on QCMs due to solar array outgassing</td>
</tr>
<tr>
<td>CCOE-2 (1979)</td>
<td>Lost 3 orders of magnitude throughput at 1.2 mm in Alpha after 9 days due to electronics box outgassing.</td>
</tr>
<tr>
<td>NOAA, TERRA, and DMSP (1978)</td>
<td>Thermal control problem due to outgassing and engine plume deposition.</td>
</tr>
<tr>
<td>RCA and GE Spacecraft (1970)</td>
<td>Thermal control problems due to contamination build-up on CBUs.</td>
</tr>
<tr>
<td>SCATHA (1979)</td>
<td>Continuous accumulations of 200 Angstrom layer were present and were fixed due to photolithographic processing.</td>
</tr>
<tr>
<td>SNM (1980)</td>
<td>Improved version of GOES-8 1.3 mm antenna instrument lost 2 orders of magnitude in throughput at 1.3 mm in Alpha within 49 days.</td>
</tr>
<tr>
<td>SEVIR (1981)</td>
<td>Accretion and photolithographic contamination on spectrograph plate calibration system.</td>
</tr>
<tr>
<td>TANSAT (1983)</td>
<td>Vent effluent deposited on solar panel radiator surface, resulting in internal contamination and ionization.</td>
</tr>
<tr>
<td>SDO (1986)</td>
<td>Degradation of 0.05-0.005 nm channel after launch, due to contaminant build-up.</td>
</tr>
<tr>
<td>LEM (1990)</td>
<td>Measured Shuttle contaminant levels, used to identify problems with particle clouds and pressure outgassing.</td>
</tr>
<tr>
<td>CNOE (1991)</td>
<td>Measured contaminant levels on the Shuttle bay, measured internal contamination due to aerosol or xenon propellant.</td>
</tr>
<tr>
<td>HST/Proj (1992)</td>
<td>Immediately lost 1200-1600 Angstrom bands due to build-up of silicones, explosives, and DOP.</td>
</tr>
<tr>
<td>IBIS (1992)</td>
<td>Visible range instrument degraded 0% (in throughput).</td>
</tr>
<tr>
<td>HST/WD (1993)</td>
<td>UV capability lost due to contamination build-up on cold CCDs combined with UV (from earth albedo) exposure.</td>
</tr>
<tr>
<td>HST/WD-2 (1994)</td>
<td>WFC2 had a prelaunch cleaning and bakeout procedure, careful design of venting protocols to protect the optical bench area, and inclusion of Zerodur molecular在外缘的。</td>
</tr>
<tr>
<td>Yohkoh (1991)</td>
<td>After only 2 years in orbit, CCD still collected some contaminants which were believed to be wettable and required CCDs randomized at 20°C every 3 months.</td>
</tr>
<tr>
<td>HST/ST/1 (1992)</td>
<td>STIS CCD sensitivity is dropping slowly across the order, but more rapidly below the Lyman alpha (121.6 cm) and beyond 159 cm due to contamination similar to that which affected the first generation HST instrument.</td>
</tr>
<tr>
<td>HST/NMCG (1994)</td>
<td>Delays at top of the detector were anti-reflective paint or a detached film deposited on the optical bench. These marks formed at the end of the detector and are characterized by small areas of reduced sensitivity.</td>
</tr>
<tr>
<td>Frequent (2002)</td>
<td>Frequent black DM structure observed in the Lyman alpha at 121.6 cm, or 121.6 cm in wavelength, due to debris and particles that prevented a valve from sealing properly, allowing propellant to leak into the engine.</td>
</tr>
<tr>
<td>Cassini (2003)</td>
<td>Narrow-angle camera with binary vision, non-intrinsic spot. The problem was fixed by a sense of gentle heating procedure.</td>
</tr>
<tr>
<td>Aruba (2002)</td>
<td>The failure caused a complete shutdown of one of Aruba's two solar arrays because the drive mechanism was contaminated by pollution of a metallic oxide.</td>
</tr>
</tbody>
</table>
On-Orbit CC Issues

  - 702-model solar array concentrations may be to blame for power failures

- “First Cassini Saturn Pictures Confirm Camera Problem Fixed”, November 18, 2002, Space News
  - Narrow-angle camera with blurry vision seen in star images
  - A series of gentle heating procedures fixed the problem

  - The failure caused a complete shutdown of one of Arabsat 3A’s two solar array
  - Drive mechanism was contaminated by pollution of metallic origin

- TIRS Instrument on LDCM has a 25 micron particle on its filter, 4% performance degradation
Contamination control begins with conceptual design.

Most contamination-sensitive surfaces or subassemblies may be identified at the start of a program, so that accommodating the needs of the sensitive elements may be incorporated into all phases of the program.
  - Protect the most contamination-sensitive surfaces

The conceptual design must identify a configuration that isolates sensitive elements from contamination sources and permits assembly, test, inspection, and cleaning, with minimal impact to the system.

It is far easier to design contamination control into the project from the start than it is to retrofit it in after the fact.

Involving contamination knowledgeable personnel in the early stages of the design process is the most effective way to accomplish this.

If done properly, effective contamination control can be done at minimal cost, and inconvenience, to the program.
The Contamination Control Approach

1. Mission Objectives
2. Instrument Design
3. Maximum Allowable Degradation
4. Contamination Requirements
5. Environments Data Base
6. Contamination Prediction Model (Molecular, Particulate)
7. Sensitivity Model (Molecular, Particulate)
8. Performance Model
9. Contamination Control Plan (CCP)
10. Performance Acceptable?
   - Yes: Finalize CC RQMTS
     - Implement CCP
     - Monitor Environments
   - No: Continue Mission
11. Cost Tradeoffs
12. Improve Environments
13. Design Protective Devices (covers, etc.)
14. Special Cleaning, Additional Bakeouts
15. Change Sensitivities/RQMTS (Mission Goals)
Contamination Effects
Satellite Example: Lunar Reconnaissance Orbiter

SPACECRAFT BUS

INSTRUMENT MODULE

ISO-THERMAL PANEL/RADIATOR

HIGH GAIN ANTENNA SYSTEM

PROPULSION MODULE

SOLAR ARRAY SYSTEM

TFAWS 2015 – August 3-7, 2015
Contamination Effects on Hardware Performance

• Particle
  – Obscuration
  – Absorption
  – Scattering
  – Mechanical Interference, sticking, clogging
  – systems and moving mechanisms
  – If conductive, shorting

• Molecular
  – Absorption (affects transmission, reflectance)
  – Scattering (dependent upon deposition pattern)
  – Sticking in mechanical mechanisms
  – Corrosion during ground operations can cause particulates
Impacts of Contamination Effects

Particle Effects:

- **Affects Signal Strength:**
  - Reflective Mirrors/Detectors/Micro-Channel Plates
- **Scatter:**
  - Optical Baffles/Mirrors/Lens
- **Obscuration:**
  - Radiators/Thermal Coatings/Mirrors
- **Absorption of Energy:**
  - Solar Cells/Thermal Coatings

LROC NACs Radiators
LAMP UV instrument
LOLA Laser
Star Tracker Baffles
LROC Cameras
LRO Instrument Module
Molecular Effects:
• Affects Signal Strength:
  Absorbed Laser Energy/Lens
• Scatter & Obscuration:
  Optics/Mirrors/Lens Radiators/ Thermal Coatings
• Absorption of Energy:
  Solar Cells/ Thermal heating of Coatings/Lens/Optics
• Synergistic Effects
Contamination Requirements
• Sensitive hardware and instruments drive contamination requirements
  – Not all hardware is sensitive to contamination, however all hardware still possess contamination requirements in order to avoid cross-contamination
• There are 2 main types of contamination requirements on flight hardware:
  – Surface cleanliness levels:
    • Molecular requirements- films, greases, skin oils
    • Particulate requirements- dust, debris, skin cells
    • Visibly Clean
  – Outgassing requirements:
    • Bake-outs are required in order to meet molecular outgassing flux levels
# Hardware Contamination Requirements

## Surface Particulate Cleanliness Levels per IEST-STD-CC-1246D

1. **Particle Distribution:**
   - Size and Count yield Cleanliness Level

   \[
   \text{Log } N = 0.926(\text{Log}^2 L - \text{Log}^2 X)
   \]

   \(N = \text{Amount of Particles in } 0.1\text{m}^2\)

   \(X = \text{Particle Size} \quad L = \text{Cleanliness Level}\)

2. **Surface Obscuration:**
   - Percent Area Coverage (PAC)

   \[
   \text{PAC} = \frac{\text{Total Area of Particles}}{\text{Total Surface Area}} \times 100
   \]

---

Log-Normal Distribution with Product Cleanliness Level
(Dave Hughes)

Particles on a surface using Image Analysis
Surface Molecular Cleanliness Levels per IEST-STD-CC1246D

Molecular NVR amount on a given surface area

<table>
<thead>
<tr>
<th>Level</th>
<th>Limit, NVR mg/0.1m² (or μg/cm²)</th>
</tr>
</thead>
<tbody>
<tr>
<td>A/100</td>
<td>0.01</td>
</tr>
<tr>
<td>A/50</td>
<td>0.02</td>
</tr>
<tr>
<td>A/20</td>
<td>0.05</td>
</tr>
<tr>
<td>A/10</td>
<td>0.1</td>
</tr>
<tr>
<td>A/5</td>
<td>0.2</td>
</tr>
<tr>
<td>A/2</td>
<td>0.5</td>
</tr>
<tr>
<td>A</td>
<td>1.0</td>
</tr>
<tr>
<td>B</td>
<td>2.0</td>
</tr>
<tr>
<td>C</td>
<td>3.0</td>
</tr>
<tr>
<td>D</td>
<td>4.0</td>
</tr>
<tr>
<td>E</td>
<td>5.0</td>
</tr>
<tr>
<td>F</td>
<td>7.0</td>
</tr>
<tr>
<td>G</td>
<td>10.0</td>
</tr>
<tr>
<td>H</td>
<td>15.0</td>
</tr>
<tr>
<td>J</td>
<td>55.0</td>
</tr>
</tbody>
</table>

Surface molecular contamination [www.atp.ie/](http://www.atp.ie/)
Molecular Thickness

- Generally, the contamination effect is directly related to molecular thickness.
- If the density of the contaminant is known (1 g/cm³ is a reasonable value), the cleanliness level can be converted to a contaminant thickness.
- The thickness of a molecular contamination layer is typically expressed as Angstrom (Å).
- A requirement that a surface must be cleaned to level "C" means that molecular films can not exceed 3 mg per 0.1 m², or 3 μg/cm², on that surface or 300 Å in thickness.
On-Orbit Effects
On orbit, particle movement and redistribution mechanisms differ from those normally encountered on the ground

– In space, there are fewer direct forces (wind, air flow disturbances, movement) to move particles around

– In space, movement and redistribution are caused primarily caused by
  • Launch ascent depressurization (Air rushes out of vents)
  • Greatly reduced gravitational forces (Everything “floats” -- No hiding dirt under the carpet or in the corner!)
  • Absence of air pressure
  • Charging
On-Orbit Effects of Molecular Contamination

- On-Orbit molecular effects are more of a concern than particulate (molecular transport analysis).
- On the ground, Non-Volatile Residue (NVR) or Molecular Contamination deposits result from two phenomena:
  - contact with a contaminated or contaminating surface or material — contact transfer from fingerprints, adhesive tape, etc.
  - condensation of airborne molecular organic contamination
    - volatile (gaseous) organic hydrocarbons (VOC): paint, adhesives, machine lubricating greases.
- On orbit, NVR / molecular films result when materials outgas from one surface and deposit on another, usually cooler, surface.
- Contaminants inside electronic boxes can outgas and exit through the vents and deposit on colder surfaces. This is induced more due to the vacuum of space.
A Few Mechanisms for Vacuum Transport

- Diffusion limited hi-outgas molecule
- Non-outgassing molecule at temperature T

Surface Contamination

Backscatter causes Self-contamination

Collector
Contamination sensitive surface
If temperature collector < temperature source, deposition occurs
If UV light or chemical attraction, deposition enhanced
If temperature of collector is increased, evaporation and cleaning

Solar UV
Increases outgassing
Increases deposition
Polymerizes deposits
Not factor for cruise
IS Factor on Mars

Rough Surface
Higher electrical potential
Higher surface area
Both increase deposition rates

Information provided by Therese Errigo
Molecular Effects

- Cleanliness level A corresponds to a contamination thicknesses of 100Å (or 0.01 μm, or 10 nm)
- Level A will have little effect on thermal control surfaces and solar arrays

Molecular Contamination Effects (thermal control surfaces)
Molecular Contamination Effects (solar arrays)
Molecular Contamination Effects

- Maintaining cleanliness level A is, relatively speaking, not that difficult
- This is an indication of the fact that optical surfaces are often the most susceptible to contamination
Contamination Sources

<table>
<thead>
<tr>
<th>Structure</th>
<th>Epoxies, polycarbonates, polyurethanes, polyamines, polyimides, fluorocarbons</th>
</tr>
</thead>
<tbody>
<tr>
<td>Encapsulation/Potting</td>
<td>Polyurethanes, epoxies, silicones</td>
</tr>
<tr>
<td>Conformal Coatings</td>
<td>Polyurethanes, epoxies, silicones</td>
</tr>
<tr>
<td>Adhesives</td>
<td>Polyurethanes, epoxies, silicones</td>
</tr>
<tr>
<td>Tapes</td>
<td>Polyesters, acrylics, polyamides, fluorocarbons</td>
</tr>
<tr>
<td>Others</td>
<td>Acetates, epoxies, acetals, polyamides</td>
</tr>
</tbody>
</table>

(Outgassing)

- Volatile chemicals, which may be simply excess chemicals left over from improper catalyst/resin ratios, improper curing, etc., can, over time, migrate to the surface and escape into the local environment.
- This process, called *outgassing*, is responsible for the familiar odor of plastics or rubber.
Outgassing

Material outgassing = \( f \) (time, activation energy, temperature)

Materials Outgassing Processes

(ii) Diffusion is the homogenization that occurs from random thermal motions
- Contaminants that diffuse to the surface of a material may have enough thermal energy to escape the surface forces and simply evaporate into the local environment
- Diffusion has a mid-range temperature dependence and mid-range time constant
- Diffusion is responsible for outgassing from organic materials and it is the mechanism that is the major source of outgassing on orbit

Diffusion

The amount of mass loss due to diffusion \((t^{1/2})\) can be represented by the relation

\[
\frac{dm}{dt} (t, T) = C m e^{\frac{E_o}{RT}} \frac{1}{\sqrt{t}} \quad (d-1)
\]

- \( \frac{kg}{sec} = \sec^{-1/2} \cdot kg / sec^{1/2} \)
- \( C \) (S^{-1}) is a normalization constant that must be experimentally determined
- \( m \) (kg) is the amount of mass contributing to the outgassing
- \( E_o \) (kcal/mole) is the activation energy
- \( R \) (kcal K/mole) is the gas constant
- \( T \) (K) is the temperature
- \( t \) (s) is the time
Time Dependence of Materials Outgassing

- Experimental data indicate that outgassing varies either
  - i) as an exponential function of time, or
  - ii) inversely as a power of time, or
  - iii) independently of time
- This depends on the mechanism responsible for the outgassing process

Outgassing Mechanisms

<table>
<thead>
<tr>
<th>Mechanism</th>
<th>Time Dependence</th>
<th>Activation Energy (kcal/mole)</th>
<th>1/e Temperature Range $T=E_a/R$ (K)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Desorption</td>
<td>$t^{-1}$ or $t^2$</td>
<td>1-10</td>
<td>500-5000</td>
</tr>
<tr>
<td>Diffusion</td>
<td>$t^{-1/2}$</td>
<td>5-15</td>
<td>2500-7500</td>
</tr>
<tr>
<td>Decomposition</td>
<td>n/a</td>
<td>20-80</td>
<td>10,000-40,000</td>
</tr>
</tbody>
</table>

Note: $1/e = 0.367871$
 $R = 1.987$ cal/mole-K
 $e^{E_a/RT} = e^{-1} \Rightarrow E_a/RT = 1 \Rightarrow T = E_a/R$

Materials Outgassing

- In addition to the time dependency, each process depends exponentially on a unique range of activation energies, $E_a$, (the energy required to initiate the process), and temperature, $T$, (the measure of the available thermal energy), according to the relation $e^{-E_a/RT}$
- The outgassing rate can be described as a reaction with its reaction rate determined by the Arrhenius Equation
  \[ k = A e^{-\frac{E_a}{RT}} \]
Outgassing Requirements require hardware bakeouts in order to meet molecular flux levels. Molecular flux levels are derived through molecular transport analysis based on field of view to sensitive components, chemical constituent of hardware, and the amount of outgassing species.

Example of ambient air offgassing

www.glare-x-plus.com
## Outgassing

<table>
<thead>
<tr>
<th>Material</th>
<th>Most Abundant Outgassed Species (During isothermal 30°C tests)</th>
</tr>
</thead>
<tbody>
<tr>
<td>3M No.59 tape</td>
<td>H₂O, acrylic ester</td>
</tr>
<tr>
<td>3M No.5 tape</td>
<td>H₂O, methyl ester</td>
</tr>
<tr>
<td>Metex Card P/N ME6</td>
<td>Methyl and phenyl silicones, H₂O, ester</td>
</tr>
<tr>
<td>Technit EMC-034 Sponge Neoprene Per MIL-R-6130 Type II</td>
<td>Hydrocarbons (C₁-C₁₆), H₂O</td>
</tr>
<tr>
<td>Cho-Seal 1215 – bonded to aluminum</td>
<td>Methyl and phenyl silicones, H₂O</td>
</tr>
<tr>
<td>Technit P/N 45-09802</td>
<td>Methyl and phenyl silicones, H₂O</td>
</tr>
<tr>
<td>Polastrip P/N 14-024</td>
<td>Phenyl and Methyl silicones, H₂O, ester</td>
</tr>
<tr>
<td>Silastic 501 RT cure</td>
<td>Dimethyl silicones, H₂O</td>
</tr>
<tr>
<td>RTV 112 RT cure</td>
<td>Methyl and phenyl silicones, H₂O</td>
</tr>
<tr>
<td>Silastic 140 RT cure</td>
<td>Methyl and phenyl silicones, H₂O</td>
</tr>
<tr>
<td>RTV 90 RT cure</td>
<td>Dimethyl silicones, H₂O</td>
</tr>
<tr>
<td>Natvar 400 vinyl tubing</td>
<td>Aliphatic and aromatic esters, H₂O</td>
</tr>
</tbody>
</table>
Thruster plumes are a potentially serious threat if the backflow is capable of reaching sensitive surfaces.

Deploying or operating mechanisms, releasing covers, dumping waste, or conducting proximity operations are all potential sources of contamination once on orbit, especially on manned spacecraft.
Surface Visibly Clean Levels per JSC-SN-C-0005

A visually clean surface free of physical debris as seen without optical aids (except corrected vision)

<table>
<thead>
<tr>
<th>VC Level</th>
<th>Incident Light Level</th>
<th>Observation Distance</th>
<th>Remarks</th>
</tr>
</thead>
<tbody>
<tr>
<td>Standard</td>
<td>≥ 50 foot-candles</td>
<td>5 to 10 feet</td>
<td>(2) (3) (5)</td>
</tr>
<tr>
<td>Sensitive</td>
<td>≥ 50 foot-candles</td>
<td>2 to 4 feet</td>
<td>(2) (3) (5)</td>
</tr>
<tr>
<td>Highly Sensitive Plus UV</td>
<td>≥ 50 foot-candles</td>
<td>6 to 18 inches</td>
<td>(3) (4)</td>
</tr>
</tbody>
</table>
Contamination Modeling

• Thruster Impingement: Plume Analysis
• Atomic Oxygen Effects
• Mass Transport Analysis
• Particle Redistribution Analysis
• Venting Analysis
• MOLKIT Analysis
S/C Design Methodology
Material Screening

Material Screening Criteria per ASTM E595

- Low Outgassing: Total Mass Loss (TML) < 1%, Collected Volatile Condensable Materials (CVCM) < 0.1%
- Water Vapor Regain (WVR) considered

- In ASTM E 595 test, a sample of the material is held at a temperature of 125°C for 24 h at a pressure of less than 7 x 10^{-3} Pa (or 5.0 x 10^{-5} torr)
  - 1 Pa = 1 N/m² = 7.5 x 10^{-3} torr
- Comparing the initial and final mass of the sample yields the change in mass, Δm, which is known as the TML

Information provided by Therese Errigo


http://outgassing.nasa.gov/, July 03, 2002
# Outgassing Parameters of Typical Spacecraft Materials

<table>
<thead>
<tr>
<th>Material</th>
<th>TML (%) at 75°C</th>
<th>TML (%) at 125°C</th>
<th>CVCM (%)</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>Adhesives</strong></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>R-2560</td>
<td>1.58</td>
<td>1.53</td>
<td>na</td>
</tr>
<tr>
<td>RTV-566</td>
<td>0.11</td>
<td>0.26</td>
<td>0.02</td>
</tr>
<tr>
<td>DC 93-500</td>
<td>0.07</td>
<td>0.08</td>
<td>0.05</td>
</tr>
<tr>
<td>DC 6-1104</td>
<td>0.29</td>
<td>0.58</td>
<td>0.03</td>
</tr>
<tr>
<td><strong>Films</strong></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Kapton FEP</td>
<td>n/a</td>
<td>0.25</td>
<td>0.01</td>
</tr>
<tr>
<td>Kapton H</td>
<td>n/a</td>
<td>1.17</td>
<td>0.00</td>
</tr>
<tr>
<td>Mylar</td>
<td>n/a</td>
<td>0.32</td>
<td>0.04</td>
</tr>
<tr>
<td>FEP Teflon</td>
<td>n/a</td>
<td>0.77</td>
<td>0.35</td>
</tr>
<tr>
<td><strong>Oils &amp; Greases</strong></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Brayco 815X</td>
<td>n/a</td>
<td>0.25</td>
<td>0.01</td>
</tr>
<tr>
<td>Braycote 803</td>
<td>n/a</td>
<td>0.24</td>
<td>0.13</td>
</tr>
<tr>
<td>Krytox 143AD</td>
<td>n/a</td>
<td>28.54</td>
<td>5.71</td>
</tr>
<tr>
<td>Vakote MLD73-91</td>
<td>0.40</td>
<td>n/a</td>
<td>n/a</td>
</tr>
<tr>
<td><strong>Paints &amp; Coatings</strong></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>S13GLO</td>
<td>n/a</td>
<td>0.30</td>
<td>0.03</td>
</tr>
<tr>
<td>Chemglaze Z306</td>
<td>2.40</td>
<td>2.52</td>
<td>0.07</td>
</tr>
<tr>
<td>DC Q9-6313</td>
<td>0.40</td>
<td>0.39</td>
<td>n/a</td>
</tr>
<tr>
<td>Aremco 569</td>
<td>2.28</td>
<td>3.58</td>
<td>n/a</td>
</tr>
<tr>
<td>LMSC 1170</td>
<td>1.88</td>
<td>2.89</td>
<td>n/a</td>
</tr>
<tr>
<td>YB71</td>
<td>n/a</td>
<td>2.48</td>
<td>0.00</td>
</tr>
<tr>
<td>Z93</td>
<td>n/a</td>
<td>2.60</td>
<td>0.00</td>
</tr>
</tbody>
</table>
Material Screening Continued

- ASTM E 1559: Measure molecular outgassing with TQCM (MOLKIT)
  - *Standard Test Method for Contamination Outgassing Characteristics of Spacecraft Materials*
  - ASTM E 595 screening test maintains the outgassing source and collector at fixed temperatures, it does not provide complete insight into the outgassing characteristics of a material:
    - 125°C and 25°C; 24 hours
  - It is often necessary to conduct more detailed tests to determine outgassing characteristics over a wider temperature range and determine relevant time dependencies
  - ASTM E 1559 is capable of determining both the total mass flux evolved by a material when exposed to a vacuum environment and the deposition of the outgassed flux on surfaces held at various specified temperatures
QCMs

- ASTM E 1559 utilizes Quartz Crystal Microbalances (QCMs) to make measurements of outgassed matter at different temperatures.
- A QCM compares the resonance frequency of a shielded quartz crystal, which remains contamination free, with one that is exposed to the environment and experiences a deposition of contamination.
- By calibrating the QCM, the amount of mass deposition can be determined.
Outgassing Measurements

ASTM E 595
Measures the outgassing potential

Outgassing source at 125°C

Receiver at 25°C
TML, CVCM, WVR

ASTM E 1559
Measures the deposition rate due to outgassing

Outgassing source at a defined temperature

QCMs at multiple temperatures
Transient rate
Contamination Transport

- The amount of contamination that is produced by a spacecraft is important, but the amount of contamination that reaches, and sticks to a sensitive surface is much more critical.
- In general, transport processes are generally either line of sight or non-line of sight.
- The outgassing view factor bears a strong resemblance to the thermal view factor, or angle factor, used in radiative heat balance.
  - Analogy
  - Use to derive source outgassing rate as well as estimate the surface deposition due to outgassing.

<table>
<thead>
<tr>
<th>Radiation Heat Transfer</th>
<th>Material Outgassing Transport</th>
</tr>
</thead>
<tbody>
<tr>
<td>Spectral and directional distribution</td>
<td>Lambertian distribution</td>
</tr>
<tr>
<td>Radiance, ( L_4 ) (W m(^{-2}) sr(^{-1}))</td>
<td>( M_1 ) (kg m(^{-2}) sec(^{-1})) = ( \frac{d m_1}{d t} ) (1/dA)</td>
</tr>
<tr>
<td>Emissance, ( M_1 ) ( (W m^{-2}) = \pi L_4 ) (W m(^{-2}) sr(^{-1})) [M_1 \text{ presents emissive power}]</td>
<td>( M_1 ) presents outgassing rate OGR(_{	ext{dA}1})</td>
</tr>
<tr>
<td>Exitance, ( M_1 )</td>
<td>( E_0 = \pi I_0 ), Total blackbody emissive power = ( \pi \times \text{Blackbody intensity} )</td>
</tr>
<tr>
<td>Transfer</td>
<td>OGR(<em>{12}) (kg m(^{-2}) sec(^{-1})) = OGR(</em>{\text{dA}1}) F(_{12})</td>
</tr>
<tr>
<td>( q_{12} ) (W m(^{-2})) = ( M_1 F_{12} ) [Total heat transfer from dA(_1) to dA(_2)]</td>
<td>Outgassing transfer from dA(_1) to dA(_2)</td>
</tr>
<tr>
<td>Deposition</td>
<td>( \frac{\Delta m}{\Delta t} ) (kg sec(^{-1})) = ( M_1 F_{12}; \rho_c ) [Contamination thickness ( \Delta x ) on receiver]</td>
</tr>
</tbody>
</table>

\[
A_1 F_{12} = \int \int \cos \phi_1 \cos \phi_2 \frac{dA_1 dA_2}{\pi n_{12}^2}
\]
Molecular Contamination Transport

\[ A_i F_{i-3} = \int \int \cos \phi_1 \cos \phi_2 \frac{dA_1 dA_2}{\pi r_{i-3}^2} \]

- **ASTM E 595**
  - TML, CVCM, WVR
- **ASTM E 1559**
  - Outgassing rate
- **Vent, Dump, Engine Exhaust**
- **Contamination Source Surface 1**
- **Primary Receiver Surface 2**
- **Secondary Receiver Surface 3**

- **1246**
  - Thickness
- **Effects**
  - \( \alpha, \varepsilon \)
  - Observation Throughput Scattering

TFAWS 2015 – August 3-7, 2015
Material Mitigations

- Low Particulating (minimize / avoid bare aluminum, woven textiles, Velcro)
- Avoid materials detrimental to your sensitive components (Silicones, Helium)
- Minimize quantity of organics (minimize thickness, bond lines)
- Bakeout under vacuum to reduce outgassing
On-Orbit Mitigations

- On-orbit outgassing
- Vent control
- Protective cover
- Plume shield
- Decontamination
- Purge
- Collecting devices
- Operational control
- Modeling
- In-flight monitor
• Keep sources of organics out of line of sight of optics/inlets
• Get electronics out of optic cavities whenever possible
• Keep main apertures sealed
• Isolate hazards from sensitive items (e.g., barriers, baffles, doors, covers, vents, etc.) and direct venting into non-sensitive areas
• On-Orbit Deployable Covers/Doors
• Red-Tag Covers
Other S/C Design Methodologies

• Venting
  – direct effluent away from apertures/inlets
    – MLI flaps
• Minimize number of potential vents / unintentional vents; use directional venting
• Use molecular adsorbers
• Seal Honeycomb Edges
• Purge interface/Manifold on S/C for T-0 purging

SDO Vents/Adsorbers are also cost saving to reduce bakeout time
• Selection of Thermal Control Coatings
  – sources lower temperature than collectors (sensitive surfaces)
  – provisions to heat contaminated surfaces so they release condensed contaminates (decontamination heaters)
• UV
  – avoid / minimize UV impingement (direct sun or albedo) on optics or surfaces in line of sight or near of optics/sensitive surfaces; darken optics
• Atomic Oxygen
  – avoid use of silicones in orbits with significant atomic oxygen
  – Design with enough material to meet erosion rate, e.g. Kapton, Teflon
• Plume / vents
  – direct all thruster plume and backscatter away from sensitive surfaces
  – use high purity fuel
  – Plume analysis determines impact
Contamination Effect on TCS

- Molecular contamination effect on TCS
  - Reflecting or radiating surfaces
  - Transmitting surfaces
  - Cryogenic surfaces and thin molecular films
- Particulate contamination effect on TCS
Reflecting or Radiating Surfaces

Emitting and Receiving Surfaces

Contamination affects thermal properties of emitting and receiving surfaces.

As $\rho (\lambda)$ approaches zero the surface becomes transparent, while as $\tau (\lambda)$ approaches zero the surface becomes opaque.

\[ G_{\text{ref}} \text{ and } \rho (\rho = 0; \text{ transparent}) \]

\[ G_{\text{abs}} \text{ and } \alpha \]

\[ G_{\text{tran}} \text{ and } \tau (\tau = 0; \text{ opaque}) \]

<table>
<thead>
<tr>
<th>Surfaces</th>
<th>$f$</th>
<th>$g$</th>
</tr>
</thead>
<tbody>
<tr>
<td>Emitting Surface</td>
<td>Emissive power, $E$ (W/m$^2$)</td>
<td>$E_{\lambda}$ (W/m$^2$-μm)</td>
</tr>
<tr>
<td>Reflecting Surface</td>
<td>Reflected irradiation, $G_{\text{ref}}$ (W/m$^2$)</td>
<td>Spectral Irradiation, $G_{\text{ref}}$ (W/m$^2$-μm)</td>
</tr>
<tr>
<td>Absorbing Surface</td>
<td>Absorbed irradiation, $G_{\text{abs}}$ (W/m$^2$)</td>
<td>Spectral Irradiation, $G_{\text{abs}}$ (W/m$^2$-μm)</td>
</tr>
<tr>
<td>Transmitting Surface</td>
<td>Transmitted irradiation, $G_{\text{tran}}$ (W/m$^2$)</td>
<td>Spectral Irradiation, $G_{\text{tran}}$ (W/m$^2$-μm)</td>
</tr>
</tbody>
</table>

Notes:
1. The dummy variable “s” is wavelength $\lambda$ (μm)
2. Directional, spectral property, $P_s (\lambda, \theta, \phi, T)$
3. Hemispherical, spectral property, $P_h (\lambda, T)$

\[ G_{\lambda}(\lambda) = \frac{2\pi}{\int_{0}^{\pi/2} I_{\lambda}(\lambda, \theta, \phi) \cos \theta \sin \theta \, d\theta \, d\phi} \]
Reflective Surfaces

- Consider the specific case of a surface that is designed to be totally reflective, such as a mirror or a thermal radiator, but is covered with a thin layer of a contaminant film.
- The surface is a material that, (when clean), effectively satisfies the constraint $\tau(\lambda) = 0$.
- The expression for the decrease in surface reflectance as a function of contamination thickness is:
  \[ \rho^x(\lambda) = \rho(\lambda) \exp[-2\alpha_c(\lambda)x] \]
- The factor of 2 is because a ray of light would have to transverse the contaminant film, be reflected, and transverse the contaminant film a second time to avoid being absorbed.
Absorption

- Consider the absorption on a receiving surface
- A monochromatic beam of radiation having an intensity of $I_\lambda$ impinges on the layer of thickness $dx$

\[
\alpha^x (\lambda) = \alpha (\lambda) \{1 - \exp [- \alpha_c (\lambda) x]\}
\]
- where $\alpha_c (\lambda)$ is defined as the experimentally determined absorption coefficient of the contaminating layer
Absorption Coefficient of Contaminants

For a mixture of "typical" spacecraft contaminants

Absorption Coefficient ($\mu m^{-1}$)

Wavelength ($\mu m$)
Absorption Coefficient of Contaminants

- The absorption profile of a single contaminant may be noticeably different, especially in different wavebands
  - This wavelength dependence will affect instruments operating in different wavebands

![Absorption Coefficient Diagram](image-url)
Absorption Coefficient of Contaminants

- A contaminant layer would increase the solar absorptance of a reflecting surface (possibly upsetting the thermal balance of the spacecraft)
  - $\Delta \alpha$ versus thickness
On-Orbit Solar Absorption Changes

- Historically, most spacecraft experience some degradation in $\alpha_s$ after reaching orbit
- Some spacecraft have end of life (EOL) increases in $\alpha_s$ as great as 0.15 - 0.20
  - $\Delta T$emperature?
Contamination Effect on Equilibrium Temperature

If the value of either $\alpha_s$ or $\varepsilon$ is altered by contamination, either molecular or particulate, the result will be a change in the equilibrium temperature of the surface given by

$$
\frac{\Delta T}{T} = \frac{1}{4} \left[ \Delta \left( \frac{\alpha_s}{\varepsilon} \right) \frac{\Delta}{\alpha_s} \right] = \frac{1}{4} \left[ \left( \frac{\Delta \alpha_s}{\alpha} \right) - \left( \frac{\Delta \varepsilon}{\varepsilon} \right) \right]
$$
Molecular contamination will predominately be either transparent or opaque at radiating wavelengths

- If transparent, the radiating surface is basically unaffected
- If opaque, it takes over the job of the radiator

Only if there is a significant decrease in the thermal conductivity leading to the radiating surface will the equilibrium temperature of the underlying surface be changed

- Thermal conduction and thermal isolation
- Specific temperature control
Effects on High-Emissive Surfaces

- For thin (< 1 \( \mu m \)) layers of molecular contamination this is not usually the case
  - 100 Angstroms (Å)
  - No significant decrease in the thermal conductivity
- Molecular surface contamination should have little thermal effect on high-emissivity surfaces at <300 K

Effects on Low-Emissive Surfaces

- The effects of molecular contamination on low-emissivity surfaces, such as polished metals, can be dramatic
- While molecules that are transparent to wavelengths >10 \( \mu m \) will not increase the surface emissivity, and therefore not decrease the surface temperature, molecules that are opaque at these wavelengths, which most molecules are, will increase emissivity and decrease temperature
- For many situations this can be desirable, if the extra energy is radiated to space and not to some other temperature-sensitive spacecraft surface
Effects on Specularity

- Note that an additional contamination concern in thermal control pertains to thermal radiator baffles that are highly specular.
- These surfaces are used to shield the radiator from external heat sources and can cause significant backscatter into the radiator when illuminated by the Sun or Earth.
- Often the thermal designer is more concerned with the baffles than with the initial radiator, since the radiator is protected from the Sun.
  - Cooler radiator?
Effects on Transmitting Surfaces
Effects on Transmitting Surfaces

- If a contaminant film builds up on the coverslide over a solar cell, less light will be transmitted to the cell and the power output of the cell will degrade according to the relation

\[
DF(x) = \frac{\int S(\lambda) I_s(\lambda) e^{-\alpha_s(\lambda)x} d\lambda}{\int S(\lambda) I(\lambda) d\lambda}
\]

- where \( I_s(\lambda) \) (W/m) is the spectral response of the cell, a measure of how effectively the cell converts a particular wavelength of light into power

\[
\int f(x) g(x) h(x) d\lambda
\]

- It will be seen that solar array degradation calculations should assume a photochemically deposited contaminant film that will be more absorptive
  - Photochemically enhanced deposition
Effects on Cryogenic Surfaces
The contamination issue associated with cooling any part of a spacecraft, especially an IR sensor, is that the average molecular residency times are exponential functions of temperature

\[ \tau(T) = \tau_o e^{E_a/RT} \]

- On a cold surface, molecules with lengthy residence times would stick to it.
- On a warm surface, molecules would not stick to it.
Contamination on Cryogenic Surfaces

- For example, water (the most common outgassing molecule from spacecraft surfaces) resides less than a microsecond, on average, at room temperatures, but will have a residence time on the order of the age of the universe ($\sim 10^{17}$ s) on a surface at a temperature of $\sim 77$ K.
  - Cold surfaces act as "getters" for most molecules that strike them.

- The consequences of molecular contamination on cold spacecraft surfaces depend on the nature of the contamination and the sensitivity of the surface.

- Molecules that do not scatter, reflect, or absorb IR photons at the wavelength of interest are of little concern.
  - True of one-atom gas molecules (e.g. Ne, Ar), and often true of two-atom gas molecules (e.g. $\text{N}_2$, $\text{O}_2$).
  - One-atom molecules have no vibration modes, and two-atom molecules have only one vibration mode.
Particulate Effects on TCS
Effects of Particles

- First, the dust will prevent some light from reaching the underlying surface [Obscuration]
  - Some effects of particulate contamination are therefore proportional to the surface obscuration, or the percent area coverage (PAC)
  - Solar arrays, thermal control surfaces, and optical surfaces may all be degraded due to surface obscuration

- Secondly, the particles may scatter light off of its original direction of travel [Scattering]
  - This is a critical concern for many optical systems
Reflecting of Thermal Control Surfaces

- The presence of particles on a thermal control surface will have the net effect of altering its effective solar absorptance and/or emissivity.
- By design, many thermal control surfaces are chosen to have a low value of solar absorptance.
- Particles, which would typically have a higher solar absorptance than the underlying surface, would block some light from reaching the radiator directly.
  - $\alpha$: White marble (0.46), red brick (0.75), gravel (0.29)
- Most of the obscured solar flux would be absorbed by the particles rather than reflected back to space.
As a result, the particles would seek a higher equilibrium temperature than the surface on which they are sitting.

The particles would then radiate and conduct more heat to the surface than they receive in return, and the end result would be an increase in the equilibrium temperature of the surface.

By inspection, the change in solar absorptance due to particles is given by

$$\alpha_s^x = \alpha_s + \Delta \alpha_s = \alpha_{s,\text{surf}} (1 - PAC) + \alpha_{s,\text{part}} (PAC)$$
Reflecting of Thermal Control Surfaces

\[ \Delta \alpha_s = PAC \left( \alpha_{s,\text{part}} - \alpha_{s,\text{surf}} \right) \]

- Where
  - \( \alpha_{s,\text{surf}} \) and \( \alpha_{s,\text{part}} \) refer to the solar absorptance of the clean surface and particles
  - \( PAC \) is the percent area coverage of the particles

- How significant is this?
  - Level 400 is \(~0.1\%\) obscuration
  - \( \Delta \alpha_s \sim 0.001 \)
Similarly, particles will also change the effective emissivity of a surface according to the relation

$$\varepsilon^x = \varepsilon + \Delta\varepsilon = \varepsilon_{\text{surf}} (1 - PAC) + \varepsilon_{\text{part}} (PAC)$$

$$\Delta\varepsilon = PAC \left( \varepsilon_{\text{part}} - \varepsilon_{\text{surf}} \right)$$

- Consequently, it is seen that the effective increase in solar absorptance, emissivity, and equilibrium temperature is directly proportional to the PAC.
- Note that the biggest concern is to be expected if black (highly absorptive) particles are deposited on white (highly reflective) surfaces, or if white (low-emissivity) particles deposit on black (high-emissivity) surfaces.
Surface Obscuration Effects on Solar Arrays

- Because solar cells are nonimaging devices, surface obscuration at the wavelengths of interest (~0.4 - 1.1 μm) is the only effect of surface particles.
- The power reduction is not exactly equal to the PAC of those particles.
- Individual solar cells are less sensitive to surface particles than expected.
- Experiments indicate that a 1% PAC produces only a 0.2% power loss.
- This is due to the fact that the contaminated cell not only produces less power, but also becomes a resistive load also (neglecting temperature effects, which can be important if the cells are not all at the same temperature).
## Common Spacecraft Materials

<table>
<thead>
<tr>
<th>Material</th>
<th>$\alpha_s$</th>
<th>$\varepsilon$</th>
<th>$\alpha_s/\varepsilon$</th>
<th>Material</th>
<th>$\alpha_s$</th>
<th>$\varepsilon$</th>
<th>$\alpha_s/\varepsilon$</th>
</tr>
</thead>
<tbody>
<tr>
<td>Aluminum – polished</td>
<td>0.35</td>
<td>0.04</td>
<td>8.75</td>
<td>Kapton/Al</td>
<td>0.48</td>
<td>0.81</td>
<td>0.6</td>
</tr>
<tr>
<td>Beryllium – polished</td>
<td>0.4</td>
<td>0.05</td>
<td>8.0</td>
<td>In$_2$O$_3$/Kapton/Al</td>
<td>0.4</td>
<td>0.71</td>
<td>0.56</td>
</tr>
<tr>
<td>Copper – polished</td>
<td>0.28</td>
<td>0.13</td>
<td>2.2</td>
<td>Quartz Fabric/Tape</td>
<td>0.19</td>
<td>0.6</td>
<td>0.3</td>
</tr>
<tr>
<td>Stainless Steel – polished</td>
<td>0.5</td>
<td>0.13</td>
<td>3.85</td>
<td>OSR (quartz mirror)</td>
<td>0.06</td>
<td>0.81</td>
<td>0.07</td>
</tr>
<tr>
<td>Gold – on AL</td>
<td>0.26</td>
<td>0.03</td>
<td>6.5</td>
<td>FEP (5 mil)/Silver</td>
<td>0.11</td>
<td>0.8</td>
<td>0.14</td>
</tr>
<tr>
<td>Grafoil</td>
<td>0.66</td>
<td>0.34</td>
<td>1.9</td>
<td>FEP (2 mil)/Silver</td>
<td>0.08</td>
<td>0.62</td>
<td>0.13</td>
</tr>
<tr>
<td>Silicon Solar Cell</td>
<td></td>
<td></td>
<td></td>
<td>Black Paint</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>- bare</td>
<td>0.82</td>
<td>0.64</td>
<td>1.3</td>
<td>- Epoxy</td>
<td>0.95</td>
<td>0.85</td>
<td>1.12</td>
</tr>
<tr>
<td>- Si cover</td>
<td>0.82</td>
<td>0.81</td>
<td>1.0</td>
<td>- Acrylic</td>
<td>0.97</td>
<td>0.91</td>
<td>1.07</td>
</tr>
<tr>
<td>- Si cover, blue filter</td>
<td>0.78</td>
<td>0.81</td>
<td>0.96</td>
<td>White Paint</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>- Si cover, red filter</td>
<td>0.7</td>
<td>0.81</td>
<td>0.86</td>
<td>- Silicone (S13GLO)</td>
<td>0.20</td>
<td>0.90</td>
<td>0.22</td>
</tr>
<tr>
<td>- Silicate (Z93)</td>
<td></td>
<td></td>
<td></td>
<td>- Silicate (Z93)</td>
<td>0.15</td>
<td>0.91</td>
<td>0.16</td>
</tr>
<tr>
<td>- Silicate (YB71)</td>
<td></td>
<td></td>
<td></td>
<td>- Silicate (YB71)</td>
<td>0.10</td>
<td>0.91</td>
<td>0.11</td>
</tr>
</tbody>
</table>
Sun-facing surfaces

- Sun-facing surfaces are often designed to be highly reflective to minimize the amount of heat that is absorbed by the spacecraft
  - designed to enhance reflection
  - $\alpha_{\text{small}} + \rho_{\text{large}} + \tau_{\text{small}} = 1$
- If the low initial value of $\alpha_s$ is increased by contamination, the heat load to the spacecraft will increase
  - $T = f \left( \frac{\alpha_s}{\varepsilon} \right)$
  - $\alpha_s \uparrow$ Temperature $\uparrow$
  - $\varepsilon \downarrow$ Temperature $\uparrow$
Deep-space-facing surfaces

- Deep-space-facing surfaces (and many Sun-facing surfaces as well) are often designed to be highly emissive, so that radiation heat loss to space is maximized and certain parts of the spacecraft (such as infrared focal plane detectors) can be passively cooled.

- These surfaces radiate heat more effectively than they absorb it, these surfaces are usually called radiators.
  - Contaminant lowers their effective emissivity, the heat loss will decrease and the "cold" parts of the spacecraft will warm up.

\[ Q_{out} = \varepsilon A_{tot} \sigma T^4 \]
Thermal Control Hardware

Thermal Hardware
- Thermal Surface Finishes
- Insulation
- Radiators
- Heaters
- Mounting and Interfaces
- Louvers
- Heat Switches
- Phase-Change Materials
- Pump Fluid Loops
- Thermoelectric Coolers
- Heat Pipes

Thermal Control Hardware and Contamination

<table>
<thead>
<tr>
<th>Thermal Control Hardware</th>
<th>Contamination Effect</th>
</tr>
</thead>
<tbody>
<tr>
<td>Thermal Surface Finishes</td>
<td>Molecular</td>
</tr>
<tr>
<td>Insulation</td>
<td>α, ε, k</td>
</tr>
<tr>
<td>Radiators</td>
<td>α, ε, k</td>
</tr>
<tr>
<td>Heaters</td>
<td>Performance</td>
</tr>
<tr>
<td>Mounting and Interfaces</td>
<td>Performance</td>
</tr>
<tr>
<td>Louvers</td>
<td>k</td>
</tr>
<tr>
<td>Heat Switches</td>
<td>k, performance</td>
</tr>
<tr>
<td>Phase-Change Materials</td>
<td>Performance</td>
</tr>
<tr>
<td>Pump Fluid Loops</td>
<td>Performance</td>
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<tr>
<td>Thermoelectric Coolers</td>
<td>Performance</td>
</tr>
<tr>
<td>Heat Pipes</td>
<td>Performance</td>
</tr>
<tr>
<td>Others</td>
<td>Performance</td>
</tr>
</tbody>
</table>

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Contamination Control and Prevention
Establish Contamination Control Plan (CCP)
General cleanliness should be maintained during manufacturing and assembly
• Parts should be cleaned prior to assembly and as they become soiled
• Components should be cleaned prior to becoming inaccessible
• Machining/Welding/Soldering/Abrading: Should include vacuuming, wipe down
• Lubricant/Cutting Oils: Excess should be wiped
• Coatings Application: On a cleaned surfaces
• Assembly should be done in a clean area where possible and gloves should be worn
Facility Requirements per FED-STD-209E or ISO-14644-1

Clean facilities help maintain cleanliness levels and standards

Cleanroom Garments help mitigate contamination

SSDIF
Building 29
Class 10,000/ISO 7
Temperature/Humidity Control
Full Cleanroom attire

Spacecraft Systems Development and Integration Facility (SSDIF)
Contamination Control Overview Environmental Testing

- Mechanical Tests (Additional Localized Covers for Sensitive Surfaces)
  - Vibration – Bag and Purge
  - Shock – Bag and Purge
  - Acoustic – Bag and Purge
  - Mass Properties – Perform in Cleanroom or Bag and Purge
  - Spin Balance (Launch Site) – Soft Covers for Apertures/Requires Class 10k Environment (Spacecraft Pursing)

- Thermal Vacuum Bakeout and Testing
  - Chambers Certified for Surface Cleanliness and Outgassing (TQCM, RGA, Cold Finger Analysis)
  - Use of Barriers (Bakeout Box, Tents, Bagging, Covers) to Prevent Particle Fallout
  - Scavenger Plate; Cold Finger
  - Slow Re-Pressurization
  - Use of Bakeout Boxes (Shroud Within a Shroud)

- EMI
  - Bagging/Purging to Greatest Extent Possible/Internal Covers for Optics
  - Class 10k Facility, Protect Apertures.
Facility Contamination Controls

- All equipment shall be cleaned before entering any cleanroom or cleantent
  - This includes GSE, ladders, scaffolds, dollies, tools
  - A precision cleaning area shall be provided
  - Before entering the clean area remove the outer bag in the anteroom and remove the inner bag in the cleanroom/cleantent.
  - Large items needing cleaning should be scheduled well ahead of time and coordinated with Contamination Control.
- Cleanroom paper must be used for all WOAs and papers entering a clean area
- Materials brought into the cleanroom shall be cleanroom compatible, if uncertain, contact Contamination Control
- Cleanroom doors and cleantent entrances should not be opened unless all hardware in the room/tent is in a safe configuration
- Access Restrictions: Required GSFC Code 540 Cleanroom Certification Course
- Manloading Restrictions
- Work downstream of airflow
Personnel Control Reminders

- Dust collects even within cleanrooms
- Fingerprints can not be completely removed by an alcohol wipe, and on many materials can etch the surface causing permanent changes to the surface properties.
- Particles that reside on a surface for a long period of time are harder to clean off.
- No make-up, perfume, or after shave are allowed in the clean area
- PEOPLE ARE DIRTY

Particle Generation

No make-up, perfume, or after shave are allowed in the clean area